Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S39	57	(multidie or multi-die or stacked near die or mcm or multi-chip or multichip) near2 package and (chip or die or ic) near2 (wire or wiring or connection or conductor or interconnect or interconnection or bond) near4 (through or thru) near2 (aperture or hole or opening or window)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 15:32
L18	65	(multidie or multi-die or stacked near die or mcm or multi-chip or multichip) near2 package and (chip or die or ic) near2 (wire or wiring or connection or conductor or interconnect or interconnection or bond) near4 (through or thru) near2 (aperture or hole or opening or window)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 15:32
L17	176	(interposer or carrier near substrate) and (mcm or multichip or multidie or (plural or multiple or stacked or plurality or multi or bottom or back) near2 (chip or die or ic or module)) and (interposer or carrier or substrate) near2 (aperture or opening or recess or receptacle or window) near2 (chip or die or ic or wirebond or bonding near wire or wire near bond or pillar or interconnect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 15:29
S30	162	(interposer or carrier near substrate) and (mcm or multichip or multidie or (plural or multiple or stacked or plurality or multi or bottom or back) near2 (chip or die or ic or module)) and (interposer or carrier or substrate) near2 (aperture or opening or recess or receptacle or window) near2 (chip or die or ic or wirebond or bonding near wire or wire near bond or pillar or interconnect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 15:28
S7	161	(interposer or substrate or package) near2 (cavity) near2 (die or ic) and (multidie or (plural or plurality or multiple or multi or second or secondary) near (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 15:15
L16	180	(interposer or substrate or package) near2 (cavity) near2 (die or ic) and (multidie or (plural or plurality or multiple or multi or second or secondary) near (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 15:15
L15	215	(interposer or substrate or package) near2 (recess or opening or indent or aperture or recessed or depression or depressed or receptacle) near2 (die or ic) and (multidie or (plural or plurality or multiple or multi or second or secondary) near (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 14:38
S6	201	(interposer or substrate or package) near2 (recess or opening or indent or aperture or recessed or depression or depressed or receptacle) near2 (die or ic) and (multidie or (plural or plurality or multiple or multi or second or secondary) near (die or ic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 14:37
L14	230	438/109.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 14:23
L13	478	438/108.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 14:23
L12	408	438/107.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 13:58

L11	338	257/786.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 13:38
L10	133	257/782.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 13:20
L7	258	257/724.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 13:08
L6	430	257/723.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 12:50
S8	399	257/723.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 12:25
L5	2	"6633078".pn. "5869894".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/23 11:24
L4	17	("20010004128" | "20020064900" | "20020142513" | "5506383" | "5541450" | "5639695" | "5719436" | "5869894" | "5949135" | "6172419" | "6201302" | "6326696" | "6365963" | "6414381" | "6452278" | "6469395" | "6506633").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/23 11:24
L3	417	(carrier near substrate or interposer or wiring near board or wiring near substrate) near5 (cavity or aperture or opening or depression or recess or hole or receptacle) near (die or chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 10:10
S1	346	(multidie or multi-die or stacked near die) near2 package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 10:07